PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT		
NATURE OF CONVEYANCE:	Corrective Assignment to correct the second assignee information previously recorded on Reel 023696 Frame 0090. Assignor(s) hereby confirms the Second Assignee information should appear as: Korea University Industrial & Academic Collaboration Foundation.		

CONVEYING PARTY DATA

Name	Execution Date
Chul Gyun PARK	11/20/2009
Jae Sung RIEH	11/20/2009
Dong Hyun KIM	11/20/2009

RECEIVING PARTY DATA

Name:	Samsung Electro-Mechanics Co., Ltd.	
Street Address:	314 Maetan3-dong, Yeongtong-gu	
City:	Suwon, Gyunggi-do	
State/Country:	REPUBLIC OF KOREA	

Name:	Korea University Industrial & Academic Collaboration Foundation	
Street Address:	1, Anam-dong 5 ga, Seongbuk-gu	
City:	Seoul	
State/Country:	REPUBLIC OF KOREA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12646268

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Email: awilson@ipfirm.com

Correspondent Name: LOWE HAUPTMAN HAM & BERNER

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PATENT REEL: 024174 FRAME: 0786 OF \$40.00 12646268

Address Line 4: ALEXANDRIA, VIRGINIA 22314			
ATTORNEY DOCKET NUMBER: 2336-716			
NAME OF SUBMITTER:	Benjamin J. Hauptman		
Total Attachments: 6 source=2010-04-01-Corrected_NOR_Docs#page1.tif source=2010-04-01-Corrected_NOR_Docs#page2.tif source=2010-04-01-Corrected_NOR_Docs#page3.tif source=2010-04-01-Corrected_NOR_Docs#page4.tif source=2010-04-01-Corrected_NOR_Docs#page5.tif source=2010-04-01-Corrected_NOR_Docs#page6.tif			

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):BENJAMIN HAUPTMAN COMPANY:1700 DIAGONAL ROAD

PATENT ASSIGNMENT

Electronic Version v1.1

12/23/2009 501050059

Stylesheet Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chul Gyun PARK	11/20/2009
Jae Sung RIEH	11/20/2009
Dong Hyun KiM	11/20/2009

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.		
Street Address:	314 Maetan 3-dong, Yeongtong-gu		
Internal Address:	Suwon		
City:	Gyunggi-do Gyunggi-do		
State/Country:	REPUBLIC OF KOREA		

PROPERTY NUMBERS Total: 1

Property Type	Number		
Application Number:	12646268		

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ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:

2336-716

NAME OF SUBMITTER:

Benjamin J. Hauptman

Total Attachments: 2

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PATENT

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):BENJAMIN HAUPTMAN COMPANY:1700 DIAGONAL ROAD

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PATENT

REEL: 024174 FRAME: 0789

<u>ASSIGNMENT</u>

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned, (1) PARK, Chul Gyun (4) RIEH, Jae Sung (2)____ (5) _____ (3)___ KIM, Dong Hyun who have made a certain new and useful invention, hereby sell, assign and transfer unto 1) SAMSUNG ELECTRO-MECHANICS CO., LTD. 314 Maetan3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea 2) Korea University Industrial & Academic Collaboration Foundation 1, Anam-dong 5 ga, Seongbuk-qu, Seoul, Republic of Korea its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled WIDEBAND ACTIVE CIRCUIT WITH FEEDBACK STRUCTURE (a) for which an application for United States Letters Patent was filed on , and identified by United States Serial No. 12/646,268; or (b) for which an application for United States Letters Patent was executed on_____, and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

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AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

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DATE SIGNED

Name: PARK, Chul Gyun

2009. 11. 20

2) Name: RIEH, Jae Sung

2009, 11.20

3) _____

RECORDED: 04/01/2010

Name: KIM, Dong Hyun

2009.11-20.

PATENT L: 024174 FRAME: 079